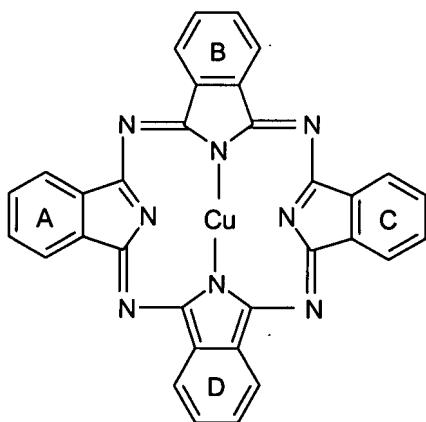


IN THE CLAIMS

The text of all claims under examination is submitted, and the status of each is identified. This listing of claims replaces all prior versions, and listings, of claims in the application.

1. (previously presented): A photosensitive resin composition comprising as a component (A) a green colorant of the formula



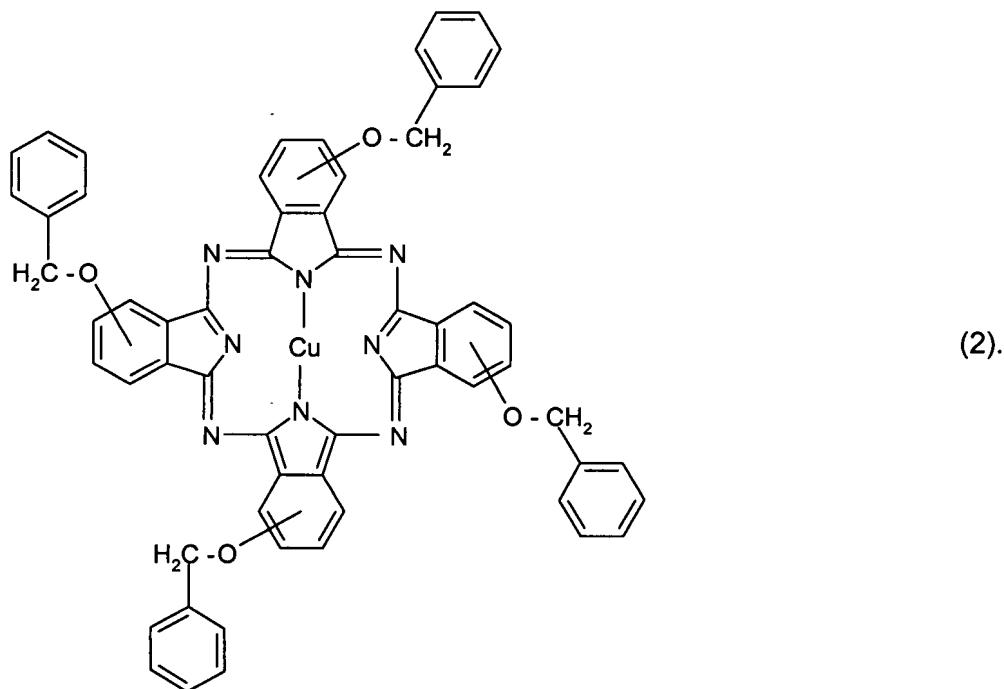
(1)

in which the rings A, B, C and D are substituted by hydroxy or by the moiety $-O-(CR_1R_2)_n-$  ,

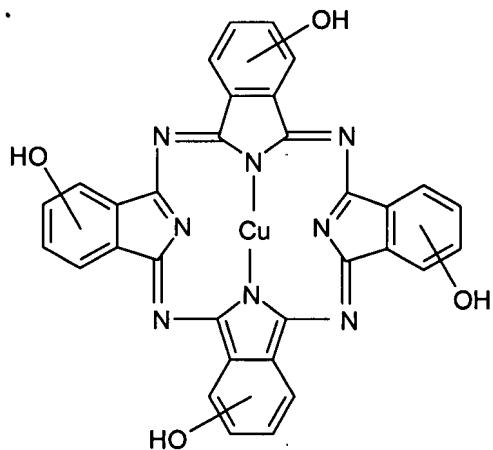
wherein R₁ is hydrogen or C₁-C₄-Alkyl, R₂ is hydrogen or C₁-C₄-Alkyl, n is 0, 1, 2 or 3 and the ring E is unsubstituted or substituted by C₁-C₆alkyl, C₁-C₆alkoxy, hydroxy, NHCO₂R₃, NHSO₂R₄ or SO₂NHR₅, wherein R₃ is C₁-C₄-Alkyl or phenyl, R₄ is C₁-C₄-Alkyl or phenyl and R₅ is C₁-C₄-Alkyl or phenyl,

- b) as a component (B) an alkali soluble reactive or unreactive oligomer or reactive or unreactive polymer ,
 - c) as a component (C) a polymerizable monomer,
 - d) as a component (D) a photoinitiator,
 - e) as a component (E) an epoxy compound,
- and also, if desired,
- f) as a component (F) further additives.

2. (original): A photosensitive resin composition according to claim 1, wherein the component (A) is the colorant of formula



3. (original): A photosensitive resin composition according to claim 1, wherein the component (A) is the colorant of formula



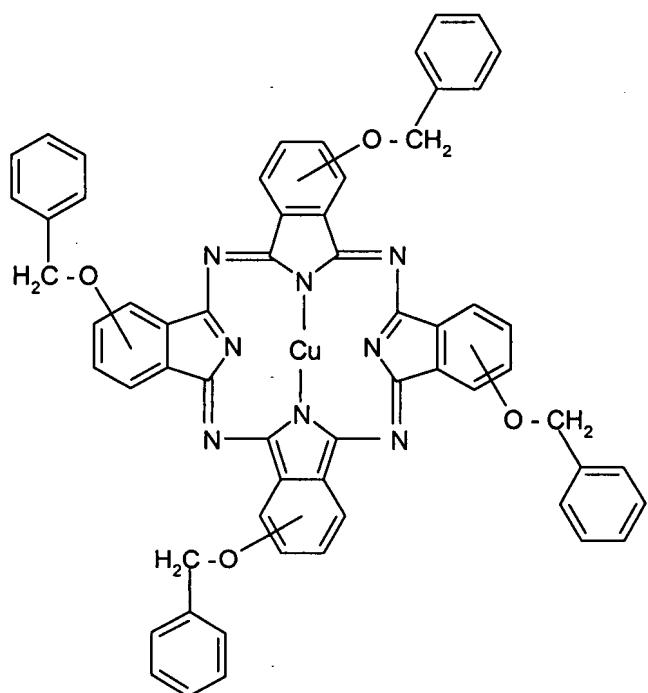
(3).

- 4. (withdrawn):** Solder resist process, which process comprises the steps of
(1) mixing the components (A) to (E) and if desired (F) according to claim 1,
(2) applying the resulting composition to the substrate to generate a coated substrate,
(3) evaporating the solvent, if present, at a temperature between 80-90°C,
(4) exposing the coated substrate to irradiation through a negative mask or by a direct laser imaging,
(5) developing the irradiated sample by washing with aqueous alkaline solution and thereby removing the uncured areas,
and
(6) thermally curing the sample at a temperature about 150°C, thereby initiating the crosslinking between the carboxylic acid and the epoxy component.

- 5. (withdrawn):** Coated substrate obtained by the process according to claim 4.

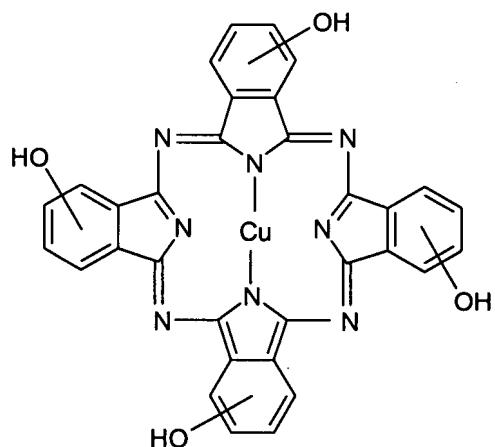
- 6. (previously presented):** Substrate coated with the photosensitive resin composition according to claim 1.

- 7. (withdrawn):** Solder resist process according to claim 4, wherein component (A) of step (1) is the colorant of formula



(2).

8. (withdrawn): Solder resist process according to claim 4, wherein component (A) of step (1)) is the colorant of formula



(3).

9. (withdrawn): Coated substrate obtained by the process according to claim 7.

10. (withdrawn): Coated substrate obtained by the process according to claim 8.

11. (previously presented): Substrate coated with the photosensitive resin composition according to claim 2.

12. (previously presented): Substrate coated with the photosensitive resin composition according to claim 3.

13. (new): A photosensitive resin according to claim 1, wherein the polymerizable monomer is a vinyl monomer.